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Abstract of the Disclosure

[0041] A thrust pad assembly which is capable of reducing the quantity of metal electroplated onto the edge region of a substrate to eliminate or reduce the need for edge bevel cleaning or removal of excess metal from the substrate after the electroplating process. The thrust pad assembly includes an air platen through which air is applied at variable pressures to the central and edge regions, respectively, of a thrust pad. The thrust pad applies pressure to a contact ring connected to an electroplating voltage source. The contact ring applies relatively less pressure to the edge region than to the central region of the substrate, thereby reducing the ohmic contact.